

	Current OR	Current XRef	Retrieval Classif	Inventor	S	C	P	2
1	257/774	257/778; 257/786; 438/629; 438/666		Trivedi, Pradeep et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
2	257/748	257/750; 257/781; 257/786; 257/E23.02		Heim, Dorothy A.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
6	257/758	257/680; 257/700; 257/701; 257/773; 257/774; 257/775; 257/784; 257/786; 257/788; 257/E23.02		Lee, Sueng-Rok et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
8	257/786	257/763; 257/764; 257/915; 257/E23.02; 257/E23.037; 257/E23.049; 257/E23.128		Rostoker, Michael D. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
9	257/773	257/774; 257/775; 257/786; 257/E23.02; 257/E23.152		Nozaki, Masahiko	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
10	257/781	257/698; 257/E23.02		Fujiki, Noriaki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

	U	1	Document ID	Issue Date	Pages	Title
1	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6566758 B1	20030520	11	Current crowding reduction technique for flip chip package technology
2	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5248903 A	19930928	8	Composite bond pads for semiconductor devices
6	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 6313537 B1	20011106	25	Semiconductor device having multi-layered pad and a manufacturing method thereof
8	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5404047 A	19950404	23	Semiconductor die having a high density array of composite bond pads
9	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5502337 A	19960326	16	Semiconductor device structure including multiple interconnection layers with interlayer insulating films
10	<input type="checkbox"/>	<input checked="" type="checkbox"/>	US 5736791 A	19980407	17	Semiconductor device and bonding pad structure therefor

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	2250	vias with (bump or ball) and (metal\$5 or conducti\$3 or wir\$3) near (layer or film)	USPA T	2003/10/05 20:52
2	BRS	2088	(vias with (bump or ball) and (metal\$5 or conducti\$3 or wir\$3) near (layer or film)) and (semiconductor or chip or (integrated near circuit) or die or IC)	USPA T	2003/10/05 20:55
3	BRS	1597	((vias with (bump or ball) and (metal\$5 or conducti\$3 or wir\$3) near (layer or film)) and (semiconductor or chip or (integrated near circuit) or die or IC)) and "257"	USPA T	2003/10/05 22:05
4	BRS	1	"5248903".PN.	USPA T	2003/10/05 21:01
5	BRS	1	"5700735".PN.	USPA T	2003/10/05 21:02
6	BRS	1	"5736791".PN.	USPA T	2003/10/05 21:03
7	BRS	1	"5962919".PN.	USPA T	2003/10/05 21:03
8	BRS	1	"6306749".PN.	USPA T	2003/10/05 21:04
9	BRS	1	"6448641".PN.	USPA T	2003/10/05 21:04

	Type	Hits	Search Text	DBs	Time Stamp
10	BRS	491	((vias with (bump or ball) and (metal\$5 or conducti\$3 or wir\$3) near (layer or film)) and (semiconductor or chip or (integrated near circuit) or die or IC)) not (((vias with (bump or ball) and (metal\$5 or conducti\$3 or wir\$3) near (layer or film)) and (semiconductor or chip or (integrated near circuit) or die or IC)) and "257"))	USPA T	2003/10/05 22:05
11	BRS	1	"5248903".PN.	USPA T	2003/10/05 22:25
12	BRS	1	"5404047".PN.	USPA T	2003/10/05 22:25
13	BRS	1	"5502337".PN.	USPA T	2003/10/05 22:26
14	BRS	1	"5736791".PN.	USPA T	2003/10/05 22:26
15	BRS	1	"5739587".PN.	USPA T	2003/10/05 22:27
16	BRS	1	"5751065".PN.	USPA T	2003/10/05 22:27

	Type	Hits	Search Text	DBs	Time Stamp
1	BRS	2920	257/774	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_ TDB	2003/10/06 00:36
2	BRS	3353	257/778	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_ TDB	2003/10/06 00:37
3	BRS	2283	257/786	USPA T; US-P GPUB ; EPO; JPO; DER WEN T; IBM_ TDB	2003/10/06 00:37